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Dated: July 1, 2005

Signature: \_\_\_\_\_

(Michael R. Hull)

Docket No.: 30205/38081A  
(PATENT)

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

In re Patent Application of:  
Jae H. Kim et al.

Application No.: 10/719,135

Confirmation No.: 2226

Filed: November 21, 2003

Art Unit: 1755

For: Chemical Mechanical Polishing Slurry for  
Ruthenium Titanium Nitride and Polishing  
Process Using the Same

Examiner: Michael A. Marcheschi

**AMENDMENT IN RESPONSE TO FINAL OFFICE ACTION**  
**(37 C.F.R. §1.116)**

MS AF  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Dear Sir:

**INTRODUCTORY COMMENTS**

In response to the final Office Action dated May 4, 2005, please amend the above-identified U.S. patent application as follows:

**Amendments to the Claims** are reflected in the listing of claims which begins on page 2 of this paper.

**Remarks/Arguments** begin on page 5 of this paper.